



# CERN Beam Instrumentation Group

**Document Type: Functional Specifications**

## **VME FMC Carrier Functional Specifications.**

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**Summary:**

The VME FMC Carrier (VFC) is a general-purpose carrier for 2 low pin count FMC (VITA 57) with VME 64x and Ethernet interfaces. The Ethernet interface is designed to be White Rabbit ([www.ohwr.org](http://www.ohwr.org)) capable.

The board use connector of the type CC-HPC-10 instead of CC-LPC-10 to accommodate some signals and power supplies required from CERN BE-BI and BE-CO on the unused pins. This breaks rule 3.9 of the standard, but still assure full compatibility with commercial low pin count mezzanines.

## History of Changes

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## **1. System monitoring and power up accessibility**

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An FPGA (System FPGA or S-FPGA) shall be dedicated to the monitoring of the board conditions and configuration as well as to provide VME and ethernet access after power up. For this purpose it shall be loaded at power up from a non volatile memory and non application dependent.

The System FPGA shall give the possibility to configure the Application FPGA via the VME bus, the ethernet bus or using a configuration previously stored in an on board non volatile memory.

The following quantities shall be monitored and/or accessible via the S-FPGA:

- Board temperature
- PCB version
- System firmware version
- Board unique ID
- Status of the FMC connectors (used or not)
- Status of the FMC power supply
- Status of the Application FPGA (configured or not)

## **2. Application FPGA**

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The FPGA(s) implementing the application logic (A-FPGA) shall have direct connection to the mezzanine user pins as specified by the VITA 57 standard.

The link between the A-FPGA and the S-FPGA should have an effective, sustainable bandwidth higher than 40MB/s to exclude that this link could become the bottleneck for the data transfer over the VME bus.

The available logic elements for the designers to implement their algorithms should be twice that of an Altera EP1S40. This should be verified with a cross mapping of an existing design.

To allow easy and fast implementation of algorithms requiring high amount of memory the A-FPGA should have full access to 2 independent ZBT SRAMs.

### 3. Interfaces

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1. VME 64x interface
2. White Rabbit capable Ethernet interface
3. P0 connectivity as defined for the CERN-BE/BI crates
4. P2 user pins
5. Front panel 50Ω input and outputs
6. FMC connectors

#### 3.1. VME 64x Interface

A fully capable VME64x interface shall be available since power up via a System FPGA (S-FPGA). The interface shall be capable of using the Geographical Addressing scheme to determine its base address or have it set manually by the user via switches or equivalent mechanism.

#### 3.2. White Rabbit capable Ethernet interface

The board shall be accessible via ethernet since power up. The implemented ethernet interface shall be White Rabbit (WR) capable.

The board will be equipped with a SFP socket to allow the user to choose the media for the communication.

The base protocol for data transfer will be a custom one chosen by BE-CO and shall give the same access possibility than the VME one.

#### 3.3. P0 connectivity as defined for the BE-BI crates

The digital connectivity on the P0 as defined for the CERN BE-BI crates shall be preserved.

	Row z	Row a	Row b	Row c	Row d	Row e	Row f
1	GND	BusLine[0]	-5V2RET	-5V2RET	HwLowByte[0]	HwHighByte[0]	GND
2	GND	BusLine[1]	-5V2RET	-5V2RET	HwLowByte[1]	HwHighByte[1]	GND
3	GND	BusLine[2]	-5V2RET	-5V2RET	HwLowByte[2]	HwHighByte[2]	GND
4	GND	BusLine[3]	-5V2	-5V2	HwLowByte[3]	HwHighByte[3]	GND
5	GND	BusLine[4]	-5V2	-5V2	HwLowByte[4]	HwHighByte[4]	GND
6	GND	BusLine[5]	-5V2	-5V2	HwLowByte[5]	HwHighByte[5]	GND
7	GND	BusLine[6]	-2VRET	-2VRET	HwLowByte[6]	HwHighByte[6]	GND
8	GND	BusLine[7]	-2VRET	-2VRET	HwLowByte[7]	HwHighByte[7]	GND
9	GND		-2V	-2V	DaisyChain1_i	DaisyChain1_o	GND
10	GND		-2V	-2V	DaisyChain2_i	DaisyChain2_o	GND
11	GND						GND
12	GND		+5V	+5V	BunchSelect[0]	LvdsTurnClockP_i	GND
13	GND		+5V	+5V	BunchSelect[1]	LvdsTurnClockN_i	GND
14	GND		+5VRET	+5VRET	BunchSelect[2]	TtlTurnClock_i	GND
15	GND		+5VRET	+5VRET	BunchSelect[3]	GND	GND
16	GND		+15V	+15V	BunchSelect[4]	LvdsBunchClockP_i	GND

17	GND		+15VRET	+15VRET	BunchSelect[5]	LvdsBunchClockN_i	GND
18	GND		-15VRET	-15VRET	BunchSelect[6]	TtlBunchClock_i	GND
19	GND		-15V	-15V	BunchSelect[7]	GND	GND

*P0 connector pin definition for the BI VME crates (slots 3-11 and 13-21)*

**BusLine[7:0]:** bidirectional bus shared by all the cards in slots 3..11 AND 13..21

**HwLowByte [7:0], HwHighByte [7:0], BunchSelect [7:0]:** input bus driven by the board in slot 12 and common to all the cards in the same slots group (3..11 OR 13..21)

**LvdsTurnClockP\_i, LvdsTurnClockN\_i:** LVDS input driven by slot 12

**LvdsBunchClockP\_i, LvdsBunchClockN\_i:** LVDS input driven by the card in slot 12

**TtlTurnClock\_i, TtlBunchClock\_i:** LVTTTL inputs driven by the card in slot 12

**DaisyChain1\_i, DaisyChain2\_i:** LVTTTL input from the previous slot

**DaisyChain1\_o, DaisyChain2\_o:** LVTTTL output to the next slot

The digital signals shall be sent to/come from the Application FPGA after the required buffering. The power supply and ground connections shall be routed to the FMC mezzanine and to the P2 connector.

Note on the power supplies: It should be tested the possibility to have those power supplies generated on board. If the quality of the generated signals would be satisfactory this solution should be preferred as it would allow switching them off when not needed and the use of BI mezzanines on non BI crates.

### 3.4. P2 user pins

The highest number possible of P2 user pins should be connected straight to the Application FPGA aiming for 40 single ended lines also configurable as 20 LVDS pairs.

To the P2 user pins shall also be connected an LVDS output from each of the PLL clock sources for the FMC mezzanines.

### 3.5. Front panel 50Ω input and outputs

2 LVTTTL 50Ω inputs and 2 LVTTTL 50Ω outputs shall be available on the front panel in lemo or equivalent format.

### 3.6. FMC connectors

The carriers shall be equipped with 2 High pin count FMC connectors and be capable to accept 2 single or 1 double standard low pin count mezzanine.

	K	J	H	G	F	E	D	C	B	A
1	NC	NC	VREF_A_M2C	GND	NC	NC	PG_C2M	GND	NC	NC
2	NC	NC	PRSN1_M2C_L	CLK0_C2M_P	NC	NC	GND	DP0_C2M_P	NC	NC
3	NC	NC	GND	CLK0_C2M_N	NC	NC	GND	DP0_C2M_N	NC	NC
4	NC	NC	CLK0_M2C_P	GND	NC	NC	GBTCLK0_M2C_P	GND	NC	NC
5	NC	NC	CLK0_M2C_N	GND	NC	NC	GBTCLK0_M2C_N	GND	NC	NC
6	NC	NC	GND	LA00_P_CC	NC	NC	GND	DP0_M2C_P	NC	NC
7	NC	NC	LA02_P	LA00_N_CC	NC	NC	GND	DP0_M2C_N	NC	NC
8	NC	NC	LA02_N	GND	NC	NC	LA01_P_CC	GND	NC	NC
9	NC	NC	GND	LA03_P	NC	NC	LA01_N_CC	GND	NC	NC
10	NC	NC	LA04_P	LA03_N	NC	NC	GND	LA06_P	NC	NC
11	NC	NC	LA04_N	GND	NC	NC	LA05_P	LA06_N	NC	NC
12	NC	NC	GND	LA08_P	NC	NC	LA05_N	GND	NC	NC
13	NC	NC	LA07_P	LA08_N	NC	NC	GND	GND	NC	NC
14	NC	NC	LA07_N	GND	NC	NC	LA09_P	LA10_P	NC	NC
15	NC	NC	GND	LA12_P	NC	NC	LA09_N	LA10_N	NC	NC
16	NC	NC	LA11_P	LA12_N	NC	NC	GND	GND	NC	NC
17	NC	NC	LA11_N	GND	NC	NC	LA13_P	GND	NC	NC
18	NC	NC	GND	LA16_P	NC	NC	LA13_N	LA14_P	NC	NC
19	NC	NC	LA15_P	LA16_N	NC	NC	GND	LA14_N	NC	NC
20	NC	NC	LA15_N	GND	NC	NC	LA17_P_CC	GND	NC	NC
21	NC	NC	GND	LA20_P	NC	NC	LA17_N_CC	GND	NC	NC
22	NC	NC	LA19_P	LA20_N	NC	NC	GND	LA18_P_CC	NC	NC
23	NC	NC	LA19_N	GND	NC	NC	LA23_P	LA18_N_CC	NC	NC
24	NC	NC	GND	LA22_P	NC	NC	LA23_N	GND	NC	NC
25	NC	NC	LA21_P	LA22_N	NC	NC	GND	GND	NC	NC
26	NC	NC	LA21_N	GND	NC	NC	LA26_P	LA27_P	NC	NC
27	NC	NC	GND	LA25_P	NC	NC	LA26_N	LA27_N	NC	NC
28	NC	NC	LA24_P	LA25_N	NC	NC	GND	GND	NC	NC
29	NC	NC	LA24_N	GND	NC	NC	TCK	GND	NC	NC
30	NC	NC	GND	LA29_P	NC	NC	TDI	SDA	NC	NC
31	NC	NC	LA28_P	LA29_N	NC	NC	TDO	SDA	NC	NC
32	NC	NC	LA28_N	GND	NC	NC	3P3V_AUX	GND	NC	NC
33	NC	NC	GND	LA31_P	NC	NC	TMS	GND	NC	NC
34	NC	NC	LA30_P	LA31_N	NC	NC	TRST_L	GA0	NC	NC
35	NC	NC	LA30_N	GND	NC	NC	GA1	12P0V	NC	NC
36	NC	NC	GND	LA33_P	NC	NC	3P3V	GND	NC	NC
37	NC	NC	LA32_P	LA33_N	NC	NC	GND	12P0V	NC	NC
38	NC	NC	LA32_N	GND	NC	NC	3P3V	GND	NC	NC
39	NC	NC	GND	VADJ	NC	NC	GND	3P3V	NC	NC
40	NC	NC	VADJ	GND	NC	NC	3P3V	GND	NC	NC

LPC Connector

LPC Connector

LPC Connector

LPC Connector

*Low pin count connector definition*

Some of the unused pins shall be connected to the BI Power supplies and grounds/return paths from the P0 connector.

If possible some of the multi gigabit transceiver pairs as defined in the High Pin Count connectors shall be populated.

The JTAG and I2C busses of the connectors shall be driven by the system FPGA in order to be able to identify the plugged mezzanines and obtain their power supply requirement without the need of configuring the Application FPGA.

The clock lines CLK0\_C2M\_P and CLK0\_C2M\_N shall come from a dedicated PLL chip with phase and delay compensation.

## **4. On Board memory**

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The static memory connected to the S-FPGA and used to store the configuration for the A-FPGA should be capable of storing more than 1 version of the firmware.

Each of the 2 ZBT SRAMS connected to the A-FPGA should have at least 16Mb organized as 32 bit words.

A DRAM module should be available to the S-FPGA for buffering of data coming from the A-FPGA before transmission and general purpose non real time storage.

## 5. Testability

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The automated test of the board shall include:

- connections verification and trace integrity
- complete memory test
- external interface test

## **6. Evaluated but not accepted functional specs**

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### **6.1. Embedded HTTP server**

It was requested to have an embedded HTTP server based either on an external uController or on an embedded one. The server would have been a general interface for the system and should have given access to the status registers in the S-FPGA as well as to the internal registers of the application for test or monitoring without the need of a dedicated expert tool. The idea is also to reduce the general effort in the design of interfaces reducing their proliferation.

For the following reasons the specification was dropped:

- the system debug should be done by experts and they will not use a HTTP application/browser for such task
- a HTTP application is not suited for operation
- to be able to access the Application FPGA register in a non expert mode (direct addressing) the HTTP server should be modified at each change of the application itself and require server and client side applications. As this cannot be neither the expert/test application nor the operational one this would not reduce the general effort.
- Giving access to the internal register via a standard browser would decrease the security level

### **6.2. P2 - FMCs connections**

It was proposed to have 16 digital connections configurable as LVDS and 8 analog ones between the P2 connector and the FMC connectors.

The signal integrity of the analog lines could not be guaranteed as they need to cross the whole carrier. Those lines could not be used but for slow signals and would therefore be better preserved if digitized their value passed as a serial link.

It would not be possible to connect bidirectional LVDS lines between 3 end points in a generic way. A more flexible solution is to pass through the Application FPGA that would act as a programmable switch. This moreover would preserve the FMC standard.

### **6.3. On board DSP**

It was proposed to have a DSP on board in addition to the A-FPGA.

The case of study proposed were mainly test related in absence of a processor in the VME crate and could nevertheless solved without any major silicon waste using the Application FPGA. In case of need of embedded software for some specific application, given the size of the A-FPGA there will be no problem instantiating a soft processor inside while leaving enough silicon for most of the applications to run.

It was suggested that some wire scanner application might require complex controls that could be better suited for a DSP than for an FPGA but the control strategy is not yet clear nor the algorithms to be used. This would be a really specific requirement of a single application and in case a real DSP would be strictly needed it could always be placed on a FMC mezzanine.

### **6.4. FMC mezzanines in the JTAG chain**

Was proposed to have the possibility to add the mezzanines to the JTAG chain with the System and the Application FPGA.

There were no identified cases where this would represent a clear advantage over having the JTAG pins of the FMC connector controlled by the system FPGA.

